

JOB DESCRIPTION - EXEMPT

Position Title:	Engineering Manager - Molding and Packaging			Position # or Level :	
Department:	Engineering		Reports to:	TBD	
Employment Status:	Full time	Pay Grade or salary range:	(List the pay grade or salary range for this position)	% Travel Required	(List % of travel for this position)

Position Summary:

This hands-on leader owns end-to-end process development, refinement and sustainment of our high mix/volume microelectronics packaging technology. Most critically, the successful applicant will leverage their core competencies in fundamental Engineering principles to design and scale a world-class Molding operation, manage the team, and influence end-to-end microelectronics process solutions for customers in our Escondido, CA factory.

Essential Duties:

- Benchmark our existing Molding process and toolset by identifying root causes impacting product quality and yield at a first principles level through detailed problem solving and supporting data analysis
- Use design of experiments to identify and validate best consumables such as mold compound, cleaning agents, and epoxies
- Develop optimized recipes that cater to a range of products and form factors while creating a strong process with margin that caters for variations in product and materials
- Work with suppliers to simulate and design optimized overmold tooling
- Lead strategic selection and deployment of required capital equipment to scale process
- Adopt best known methods for process control that efficiently monitors process health over time, taking account of changeovers, preventive maintenance and event recovery
- Broaden your knowledge through hands-on experience to extend to other microelectronics manufacturing processes
- Establish DFM rules to ensure designs and process windows are aligned for cost, quality and throughput

Minimum Qualifications:

- 7+ years of experience in Transfer- or Injection-molding Manufacturing Engineering in a volume environment
- Bachelor's degree in Mechanical Engineering or equivalent
- Track record of solving complex problems
- Solid proficiency in SolidWorks for design work and revision control
- Solid proficiency in statistical process control

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- Key Competencies:**
- Microelectronics/medical/aerospace domain knowledge not required — strong curiosity and willingness to learn these spaces matters more
 - Hands-on innovator who enjoys end-to-end product ownership involving complex systems
 - Disciplined with excellent attention to detail and robust process control
 - Strong written and oral communicator

- Preferred Skills:**
- Experience with overmolding using thermoset materials (microelectronics applications are a plus), micro-molding, or accommodating complex parts comprised of mixed materials
 - Ability to interact with and influence key stakeholders and transfer required knowledge to manufacturing team members charged with day-to-day running of the process
 - Willingness to use experience and knowledge to expand the role and impact beyond the core focus area
 - Familiarity with working in ISO 9001 and ISO 13485 environments. Understanding of AS 9100, 21 CFR Part 820, and Good Documentation Practices (GDP).

Work Environment: While performing the duties of the job, the employee is regularly required to sit, stand and/or walk for extended periods of time; use hands and fingers; reach with hands and arms; and talk and hear.
 Ability to lift 30 pounds
 Observe ESD and safety practices
 Wear cleanroom attire on occasion
 Must be a U. S. Citizen or Permanent Resident

Employee Acknowledgement:

I have read this job description, and I fully understand all my job duties and responsibilities.

Print Name	Signature	Date	
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